



SOD59A

Plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC

8 February 2016

Package information

1. Package summary

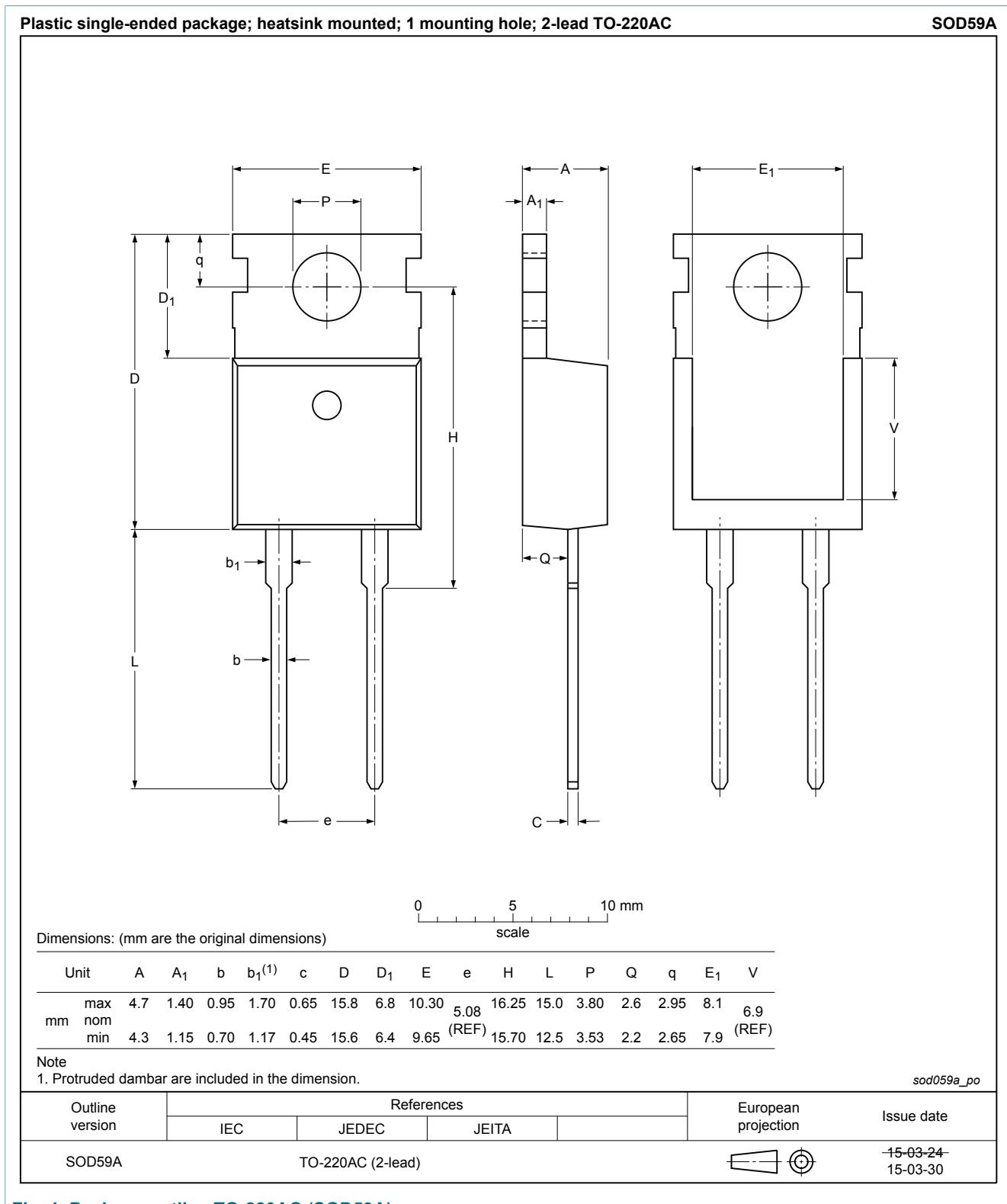
Terminal position code	S (single)
Package type descriptive code	TO-220AC
Package type industry code	TO-220AC
Package style descriptive code	SFM (single-ended flange mount)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	30-3-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	15.6	-	15.7	15.8	mm
E	package width	9.65	-	10	10.3	mm
A	seated height	4.3	-	4.5	4.7	mm
e	nominal pitch	-	-	5.08	-	mm
n ₂	actual quantity of termination	-	-	2	-	



2. Package outline



3. Legal information

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Date of release: 8 February 2016